



Product Change Notification: CAAN-19WAVG730

Date:

21-Jan-2026

Product Category:

8-Bit Microcontrollers

Notification Subject:

CCB 8025 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected AT90CAN128, AT90USB1286, AT90USB1287, AT90USB646, AT90USB647, ATmega1280, ATmega1281, ATmega2560, ATmega2561 and ATmega640 device families available in 64L TQFP (14x14x1mm) and 100L TQFP (14x14x1mm) packages at MMT assembly site.

Affected CPNs:

[CAAN-19WAVG730_Affected_CPN_01212026.pdf](#)

[CAAN-19WAVG730_Affected_CPN_01212026.csv](#)

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected AT90CAN128, AT90USB1286, AT90USB1287, AT90USB646, AT90USB647, ATmega1280, ATmega1281, ATmega2560, ATmega2561 and ATmega640 device families available in 64L TQFP (14x14x1mm) and 100L TQFP (14x14x1mm) packages at MMT assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)
Assembly Site	Microchip Technology Thailand	Microchip Technology Thailand	No

	(Branch) (MMT)	(Branch) (MMT)	
Wire Material	Au	CuPdAu	Yes
Die Attach Material	QMI519 (PFAS-free)	QMI519 (PFAS-free)	No
Molding Compound Material	G700HA	G700HA	No
Lead-Frame Material	C7025	C7025	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material at MMT assembly site.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: April 2026

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	January 2026					>	April 2026				
Work Week	01	02	03	04	05		14	15	16	17	18
Initial PCN Issue Date				X							
Qual Report Availability									X		
Final PCN Issue Date									X		

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: January 21, 2026: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_CAAN-19WAVG730_Qualification Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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